

## Inspection of bonding spots status from semi-manufactured SD card

**Application**: Inspection of bonding spots status from semi-manufactured SD card Check if the bonding spots are welding together

**NEW TRY Products**: Telecentric lens(VCM230-26) + Ring light

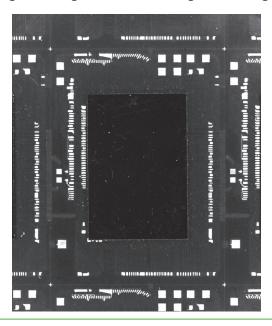
- C/F Mount Bi telecentricity;
- <0.1% distortion:
- Higt contrast:
- Clear imaging on the target area.

Camera: 5MP Basler-piA-2400-12gm, 2/3", 3.45um

• Resolution: Up to 2456\*2058 pixels.

## **Test conclusion:**

- Accuracy: Depending on different cameras resolution and image areas.
- 19.34mm × 16.21mm < 0.007mm with 2456x2058 pixels.
- Performance: Clear target imaging with high contrast makes it easy to proceed inspection.
- Test image: Achieved image with high defination and great homogeneity.



odate-20170823 www.new-try.com